

SOT617-3 DFN5050-32: plastic thermal enhanced very thin quad flat package; no leads; 32 terminals; body 5 x 5 x 0.85 mm 8 June 2016 Package information Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN32
Package type industry code	HVQFN32
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
JEDEC package outline code	MO-220
Mounting method type	S (surface mount)
Issue date	22-10-2002

Table 1. Package summary

Symbol	Parameter	Min	Тур	Nom	Max	Unit
D	package length	4.9	-	5	5.1	mm
E	package width	4.9	-	5	5.1	mm
А	seated height	-	-	0.85	-	mm
A ₂	package height	-	-	-	-	
е	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	32	-	



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2. Package outline

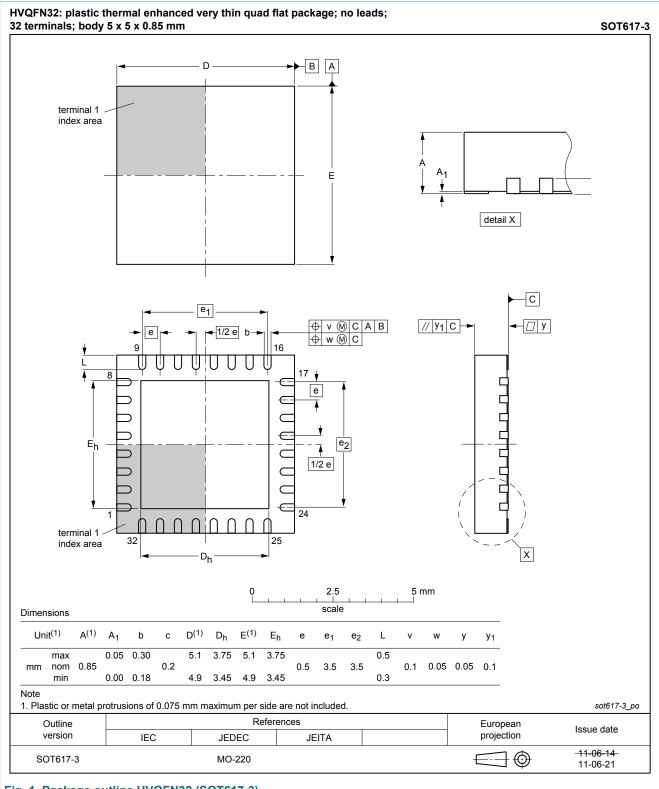


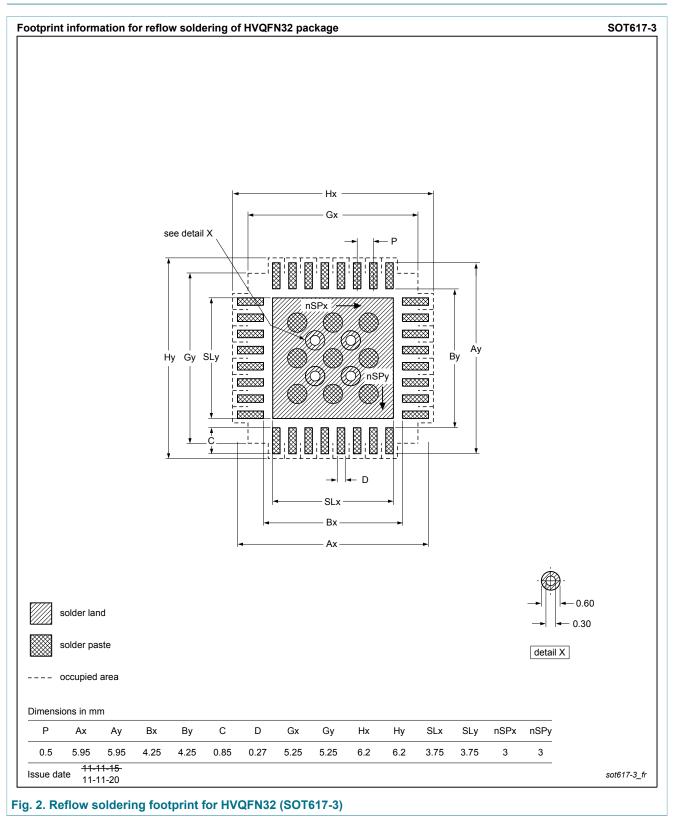
Fig. 1. Package outline HVQFN32 (SOT617-3)

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3. Soldering



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4. Legal information

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